


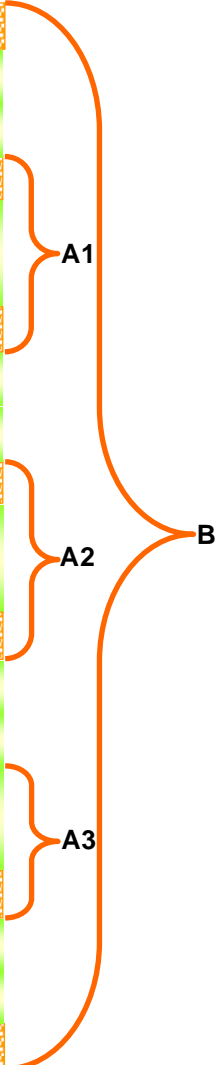













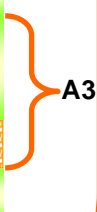

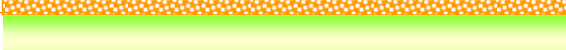


Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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07 193 FR4 90 L20.70 P10 S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

07_193_FR4_90_L20.70_p10_s1

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	90 μ	Copper			
	100 μ	Prepreg			 <p>(100 μ PrePreg-Type: 2125)</p>
	100 μ	Prepreg			
Layer-2	70 μ	Copper			
	200 μ	L-FR4			
Layer-3	70 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-4	70 μ	Copper			
	200 μ	L-FR4			
Layer-5	70 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
	200 μ	L-FR4			 <p>A3</p>
Layer-6	70 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	90 μ	Copper			

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